

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.28	100.0	5.91
			Subtotal	0.28	100	5.91
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01	100.0	0.27
	Pure metal	Aluminium (Al)	7429-90-5	0.2	100.0	4.21
			Subtotal	0.21	200	4.48
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.02	10.0	0.51
	Silver alloy	Silver (Ag)	7440-22-4	0	2.0	0.1
	Lead alloy	Lead (Pb)	7439-92-1	0.22	88.0	4.51
			Subtotal	0.24	100	5.12
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.15
	Pure metal layer	Zinc (Zn)	7440-66-6	0	0.02	0.1
	Pure metal layer	Tin (Sn)	7440-31-5	0.01	0.03	0.15
	Pure metal layer	Iron (Fe)	7439-89-6	0.03	0.11	0.54
	Pure metal layer	Copper (Cu)	7440-50-8	23.32	99.81	488.86
			Subtotal	23.37	100	489.8
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.25	100.0	5.17
			Subtotal	0.25	100	5.17
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	2.27	3.0	47.58
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.54	6.0	95.16
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	7.57	10.0	158.6
	Carbon Black	Carbon black	1333-86-4	0.38	0.5	7.93
	Filler	Misc. Silica compounds (generic)	14808-60-7	59.01	78.0	1237.08
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	1.89	2.5	39.65
			Subtotal	75.66	100	1586
			Total	100.01	100	2096.48

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